

Title (en)
BARRIER FILM FOR FLEXIBLE COPPER SUBSTRATE AND SPUTTERING TARGET FOR FORMING BARRIER FILM

Title (de)
BARRIEREFILM FÜR FLEXIBILBES KUPFERSUBSTRAT UND SPUTTERTARGET ZUR BILDUNG EINES BARRIEREFILMS

Title (fr)
FILM BARRIÈRE POUR SUBSTRAT EN CUIVRE FLEXIBLE ET CIBLE DE PULVÉRISATION POUR LA FORMATION D'UN FILM BARRIÈRE

Publication
EP 1785505 B1 20090902 (EN)

Application
EP 05766136 A 20050725

Priority

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- JP 2004232872 A 20040810

Abstract (en)
[origin: EP1785505A1] Provided are a barrier film for a flexible copper substrate comprising a Co-Cr alloy film containing 5 to 30wt% of Cr and a balance of unavoidable impurities and Co, having a film thickness of 3 to 150nm, and film thickness uniformity of 10% or less at 1Å; and a sputtering target for forming a barrier film comprising a Co-Cr alloy containing 5 to 30wt% of Cr and a balance of unavoidable impurities and Co, wherein the relative magnetic permeability in the in-plane direction of the sputtered face is 100 or less. The barrier film for a flexible copper substrate and the sputtering target for forming such barrier film have a film thickness that is thin enough to prevent film peeling in inhibiting the diffusion of copper to a resin film such as polyimide, is capable of obtaining a sufficient barrier effect even in a minute wiring pitch, and have barrier characteristics that will not change even when the temperature rises due to heat treatment or the like.

IPC 8 full level
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CPC (source: EP US)
C22C 19/07 (2013.01 - EP US); **C23C 14/205** (2013.01 - EP US); **C23C 14/3414** (2013.01 - EP US); **H05K 3/388** (2013.01 - EP US); **H05K 1/0346** (2013.01 - EP US); **H05K 1/0393** (2013.01 - EP US); **Y10T 428/12569** (2015.01 - EP US); **Y10T 428/12715** (2015.01 - EP US); **Y10T 428/12847** (2015.01 - EP US); **Y10T 428/1291** (2015.01 - EP US); **Y10T 428/31681** (2015.04 - EP US); **Y10T 428/31721** (2015.04 - EP US)

Cited by
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EP 1785505 A1 20070516; EP 1785505 A4 20080319; EP 1785505 B1 20090902; CN 101001973 A 20070718; CN 101001973 B 20100714; DE 602005016432 D1 20091015; JP 4466925 B2 20100526; JP WO2006016473 A1 20080501; TW 200606263 A 20060216; TW I271440 B 20070121; US 2007209547 A1 20070913; US 2010089622 A1 20100415; US 8318314 B2 20121127; WO 2006016473 A1 20060216

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